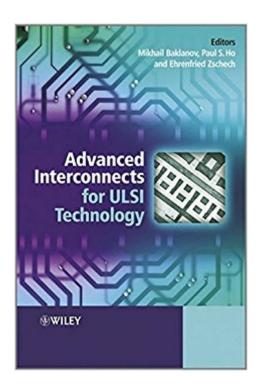


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Advanced Interconnects For ULSI Technology





Synopsis

Finding new materials for copper/low-k interconnects is critical to the continuing development of computer chips. While copper/low-k interconnects have served well, allowing for the creation of Ultra Large Scale Integration (ULSI) devices which combine over a billion transistors onto a single chip, the increased resistance and RC-delay at the smaller scale has become a significant factor affecting chip performance. Advanced Interconnects for ULSI Technology is dedicated to the materials and methods which might be suitable replacements. It covers a broad range of topics, from physical principles to design, fabrication, characterization, and application of new materials for nano-interconnects, and discusses: Interconnect functions, characterisations, electrical properties and wiring requirements Low-k materials: fundamentals, advances and mechanical properties Conductive layers and barriers Integration and reliability including mechanical reliability, electromigration and electrical breakdown New approaches including 3D, optical, wireless interchip, and carbon-based interconnects Intended for postgraduate students and researchers, in academia and industry, this book provides a critical overview of the enabling technology at the heart of the future development of computer chips.

Book Information

Hardcover: 606 pages Publisher: Wiley; 1 edition (April 2, 2012) Language: English ISBN-10: 0470662549 ISBN-13: 978-0470662540 Product Dimensions: 7 x 1.3 x 10 inches Shipping Weight: 2.4 pounds (View shipping rates and policies) Average Customer Review: Be the first to review this item Best Sellers Rank: #1,236,222 in Books (See Top 100 in Books) #47 in Books > Engineering & Transportation > Engineering > Electrical & Electronics > Circuits > VLSI & ULSI #247 in Books > Computers & Technology > Programming > Software Design, Testing & Engineering > Logic #384 in Books > Engineering & Transportation > Engineering > Electrical & Electronics > Circuits > Design

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